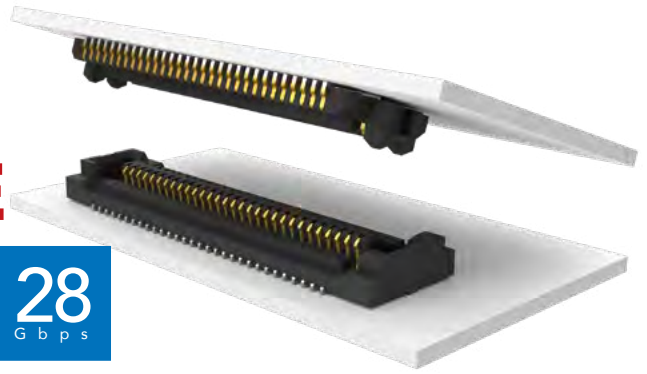


ULTRA-LOW PROFILE HEADER & SOCKET

(0.50 mm) .0197" PITCH • SLH/TLH SERIES



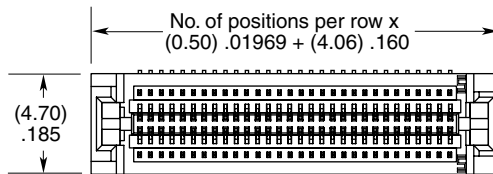
SLH
Mates:
TLH

TLH
Mates:
SLH

SLH	NO. OF POSITIONS	LEAD STYLE	PLATING OPTION	D	OPTION	OPTION
	-010, -020, -030 (Per Row)	-1.50 =1.50 mm	-G = 10 μm (0.25 μm) Gold in contact, Gold flash on tail		-A = Alignment Pin	-K = (3.00 mm) .118" DIA Polyimide Film Pick & Place Pad

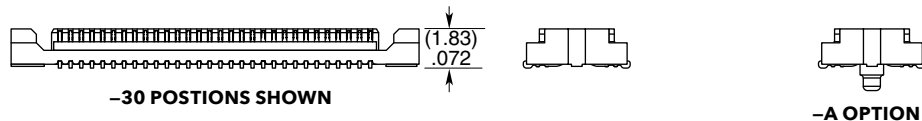
SPECIFICATIONS

Insulator Material:
Black Liquid Crystal Polymer
Contact Material:
Copper Alloy
Plating:
Au over 50 μm (1.27 μm) Ni
Current Rating:
2.1 A per pin
(2 pins powered)
Operating Temp Range:
-55 °C to +125 °C

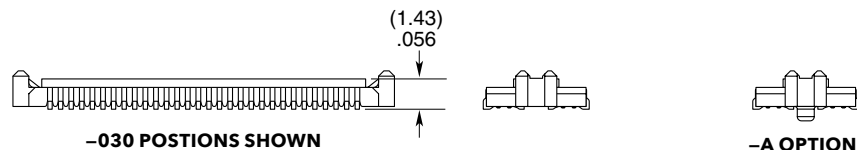
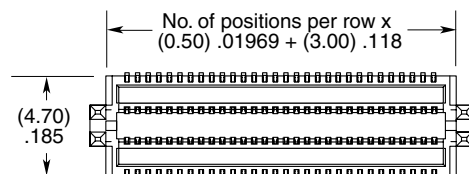


PROCESSING

Lead-Free Solderable:
Yes
SMT Lead Coplanarity:
(0.10 mm) .004" max
Board Stacking:
For applications requiring two
or more connectors per board,
contact ipg@samtec.com



TLH	NO. OF POSITIONS	LEAD STYLE	PLATING OPTION	D	OPTION	OPTION
	-010, -020, -030 (Per Row)	-0.50 =0.50 mm	-G = 10 μm (0.25 μm) Gold in contact, Gold flash on tail		-A = Alignment Pin	-K = (3.00 mm) .118" DIA Polyimide Film Pick & Place Pad



Note:
Some lengths, styles and
options are non-standard,
non-returnable.